

ABSTRACT OF THE DISCLOSURE

A method and apparatus for mounting a wafer on a wafer mount and thinning the wafer on the wafer mount. The wafer includes a front surface having bumps located thereon and a back surface. Attached to the bumps on the wafer is an adhesive tape having a backing. The wafer mount includes a suction surface with apertures that communicate with a vacuum. The wafer is mounted on the suction surface with its front surface face down with the backing of the adhesive tape abutting the suction surface of the wafer mount. The wafer is then suctioned to the wafer mount by the vacuum communicating with the apertures in the suction surface, after which, the back surface of the wafer undergoes a grinding process to thin the wafer. Since the backing attached to the bumps on the wafer is substantially planar and sits substantially flat on the suction surface of the wafer mount, the force exerted on the wafer from the thinning process does not overcome the suction force holding the wafer on the wafer mount. Thus, the bumped wafer may be thinned without damaging the bumps and the active surface of the wafer.

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